

L Number	Hits Search Text	DB	Time stamp
1	215 smart with label	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/29 10:55
2	10837 smart with card	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/29 10:55
3	90712 (flexible moveable bendable adjustable; with (substrate board pcb cb pb wd)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/29 10:55
4	19830 hard with particles	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/29 10:57
5	719715 flip bumps balls flipchip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/29 11:03
6	556 (hard with particles) same (flip bumps balls flipchip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/29 11:02
7	2 ((hard with particles) same (flip bumps balls flipchip)) and (smart with label)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/29 11:02
8	10 (smart with card) and (hard with particles)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/29 11:05
9	733 (smart with card) and (flip bumps balls flipchip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/29 11:14
10	567 ((smart with card) and (flip bumps balls flipchip)) and (chip flip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/29 11:15
11	83 (((smart with card) and (flip bumps balls flipchip)) and (chip flip)) and particles	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/29 11:06
12	25 (smart with label) and (flip bumps balls flipchip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/29 11:14
13	22 ((smart with label) and (flip bumps balls flipchip)) and (chip flip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/29 11:23

14	11882	{{(flexible moveable bendable adjustable) with (substrate board pcb cb pb wb)) and (chip flip)}	USPAT; US-PGPUB; EPO; JPO; DEFWENT; IBM_TDB	2002/07/29 11:23
15	4838	{{(flexible moveable bendable adjustable) with (substrate board pcb cb pb wb)) and (chip flip)) and (flip bumps balls flipchip)}	USPAT; US-PGPUB; EPO; JPO; DEFWENT; IBM_TDB	2002/07/29 11:23
16	4838	{{(flexible moveable bendable adjustable) with (substrate board pcb cb pb wb)) and (chip flip)) and (flip bumps balls flipchip)) and {{(flexible moveable bendable adjustable) with (substrate board pcb cb pb wb)) and (chip flip)}	USPAT; US-PGPUB; EPO; JPO; DEFWENT; IBM_TDB	2002/07/29 11:23
17	55	{{(flexible moveable bendable adjustable) with (substrate board pcb cb pb wb)) and (chip flip)) and (flip bumps balls flipchip)) and (hard with particles)}	USPAT; US-PGPUB; EPO; JPO; DEFWENT; IBM_TDB	2002/07/29 11:24